Product Change Notification

Current Date: 18-Aug-2021

TE Connectivity

Product Change Notification: PCN-21-110417 **PCN Date:** 17-AUG-21

Customer: TTI, Inc. (1305175) **Location:** Maisach-gernlinden **Agreement:** TTI001

TE would like to inform you of the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

General Product Description:
HV100 SMD Connector Single Row

Description of Changes
Plastic material change for the housings from the current LCP grade to a readily available LCP grade. No effect on functionality. New LCP grade is validated. See attached test report **Other attachments:** Test report

Reason for Changes:	
Long lead time issues with current LCP grade, need early approval to implement within next the 90 days for fulfilling the orders.	
Estimated Dates:	
Last Order Date (Obsolete Parts Only):	**First Date To Ship** (Changed Parts Only):
	24-NOV-2021
Last Ship Date (Obsolete Parts Only):	**Last Date for Mixed Shipments:** (Changed Parts Only):
	31-DEC-2021

Part Number(s) being Modified:

Part Number	Part Discontinued per PCN	Customer Drawing	Customer Part Number	Alias Part Number(s)	Substitute Part Number	Substitute Alias Part Number(s)	Description Of Difference
1241152-3	NO		TYC1241152-3				
1241152-4	NO		TYC1241152-4				
1241152-6	NO		TYC1241152-6				

The documents listed below are being modified. Related parts that are not explicitly listed on this PCN are not being modified or discontinued as per the PCN. The Last Order Date, Last Ship Date, First Date to Ship Changed Parts and last date for Mixed Shipments apply only to parts explicitly listed on this PCN.

Customer Drawing(s) Being Modified:

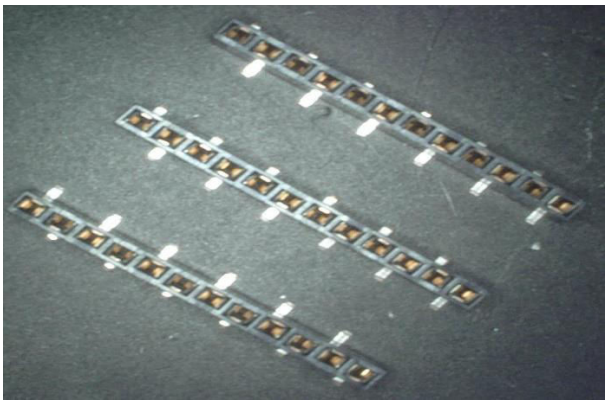
Drawing Number	Related Part Number	Customer Part Number	Current Revision	New Revision
1241152	1241152-3	TYC1241152-3		

Test Report

's-Hertogenbosch Environmental Testing Laboratory (IND)
TE Connectivity Nederland BV, Rietveldenweg 32, 5222 AR,'s-Hertogenbosch, The Netherlands

Report Title: **HV100 SMD RECEPTACLE SINGLE ROW**

Report ID: **502-153566 rev. A**
Date Issued: **27-Jul-2021**
TE Data Classification (TEC-02-04) **class I**

Requestor: **J K, Karthik**	
TE Project Number: **PRJ-21-000902070**	
Sample Name: **HV100 SMD RECEPTACLESINGLE ROW**	
TE Part number: **1-1241152-2 Rev D**	
Remarks: Samples returned to requester	

Test Scope:
To check the mechanical and electrical performance of the HV100 SMD receptacle single row connector produced with new plastic housing material, when tested according test group P, CP of the TE product specification 108-19056 and method B, condition B of the TEC-109-201 specification.

Performed Test or Analysis:

1 Visual examination	4 Dielectric withstanding voltage
2 Termination resistance	5 Damp heat steady state
3 Insulation resistance	6 Resistance to soldering heat

Requirement:
TE Connectivity Product Specification 108-19056 and TEC-109-201

Conclusion:	Result:
All tested samples met the specified requirements of TE Connectivity Product Specification 108-19056 test group P,CP and TEC-109-201 method B, condition B.	OK

Lab Project ID (lab internal):	Responsible Test Engineer:	Approver:
E21.06.3197	**Verhoeven, Ad**	**K. Schepers**

SAMPLE DESCRIPTION

The available HV100 SMD Receptacle single row connectors (P/N: 1-1241152-2 Rev D) were divided in to two groups (P, Cp and group 2).

TEST PROCEDURES

IEC 60512-1-1:
Test 1a

VISUAL EXAMINATION:
The test samples were visually inspected under a stereomicroscope, at a 10x magnification, with suitable illumination.

IEC 60512-2-1:
Test 2a

TERMINATION RESISTANCE:
The contact resistance was measured with an open circuit voltage of 20 mVolt and a maximum current of 100 mA DC, mated with a available header from ETL lab as counterpart.
For measuring points see figure 1.

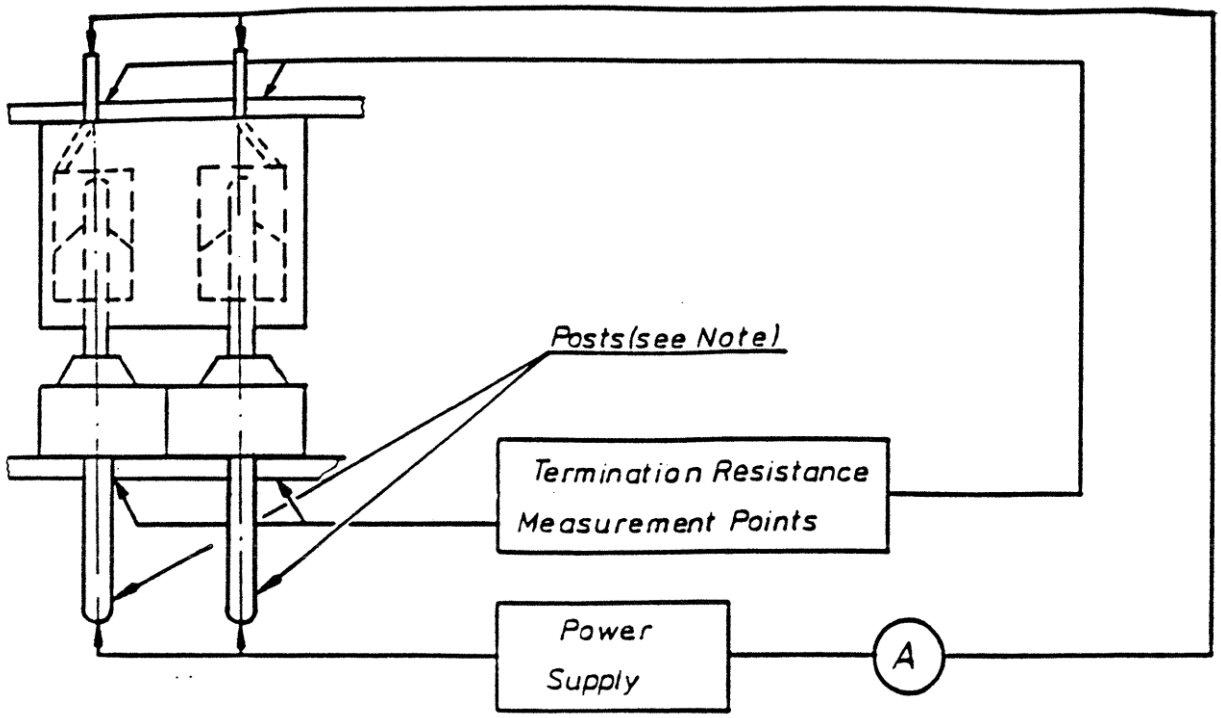


figure 1

IEC 60512-3-1:
Test 3a

INSULATION RESISTANCE:
The unmated samples are measured with a programmable electrometer. The measuring voltage was 100 Volt during one minute.

IEC 60512-4-1:
Test 4a

DIELECTRIC WITHSTANDING VOLTAGE:
The unmated samples are tested with a high voltage tester. The test duration was one minute at 1000 V_{rms}.

IEC 60512-11-3:
Test 11c

DAMP HEAT, STEADY STATE:

The samples were subjected to a damp heat steady state test under the following conditions:

Temperature : 40°C.
Rel. humidity : 95%.
Condition : unmated.
Duration : 21 days.

TEC-109-201:
§3.3 Method B, cond. B

RESISTANCE TO SOLDERING HEAT:

Samples were 3 times subjected to a Hot air reflow soldering curve, under the following conditions:

- Average ramp rate: 3°C per second maximum
- Preheat temperature (minimum): 150°C
- Preheat temperature (maximum): 200°C
- Preheat time: 60 to 180 seconds
- Ramp to peak: 3°C per second maximum
- Time over liquidus (217°C): 60 to 150 seconds
- Peak temperature: 260 +0°-5°C
- Time within 5°C of peak: 20 to 40 seconds
- Ramp - cool down: 6°C per second maximum
- Time 25°C to peak: 8 minutes maximum

TEST SEQUENCE

Group P, CP
Visual examination
Termination resistance
Insulation resistance
Dielectric withstanding voltage
Damp heat steady state
Insulation resistance
Termination resistance
Dielectric withstanding voltage
Final visual examination

Group 2
Visual examination
Resistance to soldering heat
Final visual examination

EQUIPMENT USED

Equipment	Manufacturer	Type	Series Nb	Cal. Due
Micro-Ohm meter 1	HIOKI	3560	90922733	Oct-22
Elektro meter 2	HIOKI	3560	110202069	Oct-22
High Voltage Tester 1	Sefelec	DXS506	1109582	Jan-22
Climatic chamber 70/200	C.T.S.	CS-70/200-15	167209	Feb-22
Hot air reflow oven	ALLSMT	EasyFlow	6/30	-

SUMMARY OF TESTRESULTS

TstGrp P, CP	Measurements	Requirements	Results
Termination resistance			
Initial	Max. 4.65 mΩ	Max. 20 mΩ	OK
Final	Max. 7.00 mΩ	Max. 20 mΩ	OK
Insulation resistance			
Initial	Min = 6.72E+13	Min. 1000E+09	OK
Final	Min = 8.74E+13	Min. 10E+09	OK
Dielectric withstanding voltage			
Initial	No flash over or break down		OK
Final	No flash over or break down		OK

TstGrp 2	Resistance to soldering heat	Results
	No blisters, deformation/warpage or physical damage	OK